

## 具有三态输出的 SNx4HCT373 八路透明 D 类锁存器

### 1 特性

- 4.5V 至 5.5V 的工作电压范围
- 高电流三态真实输出最多可驱动 15 个 LSTTL 负载
- 低功耗， $I_{CC}$  最大值为 80  $\mu$ A
- 典型值  $t_{pd} = 21\text{ns}$
- 电压为 5V 时，输出驱动为  $\pm 6\text{mA}$
- 低输出电流，最大值 1  $\mu$ A
- 输入兼容 TTL 电压
- 单个封装中包含八个高电流锁存器
- 针对负载的完全并行访问

### 2 说明

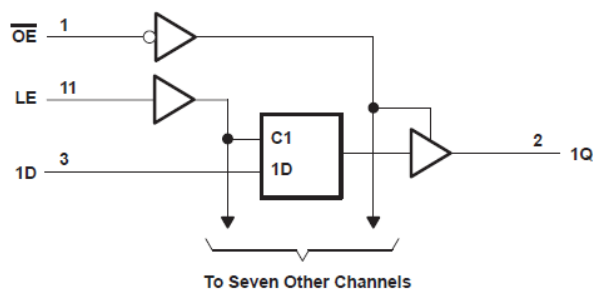
这些 8 位锁存器具有专门设计用于驱动高电容或相对低阻抗负载的三态输出。它们特别适用于实现缓冲寄存器、I/O 端口、双向总线驱动器和工作寄存器。

HCT373 器件的 8 个锁存器是透明 D 类锁存器。在锁存使能 (LE) 输入为高电平时，Q 输出将跟随数据 (D) 输出。当 LE 为低电平时，Q 输出被锁存在 D 输入上设置的电平上。

#### 器件信息

| 器件型号          | 封装 <sup>(1)</sup> | 封装尺寸 (标称值)       |
|---------------|-------------------|------------------|
| SN74HCT373DW  | SOIC (20)         | 12.80mm × 7.50mm |
| SN74HCT373N   | PDIP (20)         | 25.40mm × 6.35mm |
| SN74HCT373NSR | SO (20)           | 15.00mm × 5.30mm |
| SN74HCT373PW  | TSSOP (20)        | 6.50mm × 4.40mm  |
| SN54HCT373J   | CDIP (20)         | 26.92mm × 6.92mm |
| SNJ54HCT373FK | LCCC (20)         | 8.89mm × 8.45mm  |
| SNJ54HCT373W  | CFP (20)          | 13.72mm × 6.92mm |

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



功能方框图



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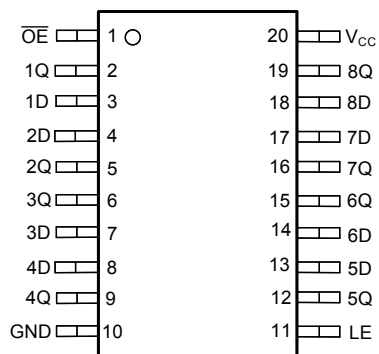
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## 3 Revision History

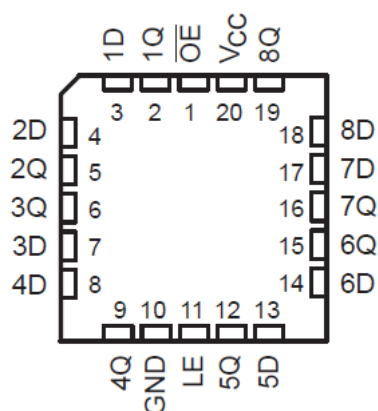
注：以前版本的页码可能与当前版本的页码不同

|                                                                                                                                                                                      |             |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|
| <b>Changes from Revision F (December 2021) to Revision G (July 2022)</b>                                                                                                             | <b>Page</b> |
| • Removed DB package.....                                                                                                                                                            | <b>4</b>    |
| <b>Changes from Revision E (December 2021) to Revision F (December 2021)</b>                                                                                                         | <b>Page</b> |
| • Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4, DB was 70 is now 122.7, PW was 83 is now 131.8..... | <b>4</b>    |
| <b>Changes from Revision D (August 2003) to Revision E (December 2021)</b>                                                                                                           | <b>Page</b> |
| • 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准.....                                                                                                                                           | <b>1</b>    |

## 4 Pin Configuration and Functions



**J, W, DB, DW, N, NS, or PW package**  
**20-Pin CDIP, CFP, SOIC, PDIP, SO, TSSOP**  
**Top View**



**FK package**  
**20-Pin LCCC**  
**Top View**

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|           |                                            |                             | MIN   | MAX      | UNIT |
|-----------|--------------------------------------------|-----------------------------|-------|----------|------|
| $V_{CC}$  | Supply voltage range                       |                             | - 0.5 | 7        | V    |
| $I_{IK}$  | Input clamp current <sup>(2)</sup>         | $V_I < 0$ or $V_I > V_{CC}$ |       | $\pm 20$ | mA   |
| $I_{OK}$  | Output clamp current <sup>(2)</sup>        | $V_O < 0$ or $V_O > V_{CC}$ |       | $\pm 20$ | mA   |
| $I_O$     | Continuous output current                  | $V_O = 0$ to $V_{CC}$       |       | $\pm 35$ | mA   |
|           | Continuous current through $V_{CC}$ or GND |                             |       | $\pm 70$ | mA   |
| $T_J$     | Junction temperature                       |                             |       | 150      | °C   |
| $T_{stg}$ | Storage temperature range                  |                             | - 65  | 150      | °C   |

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 Recommended Operating Conditions<sup>(1)</sup>

|          |                                 |                           | SN54HCT373 |     |          | SN74HCT373 |     |          | UNIT |
|----------|---------------------------------|---------------------------|------------|-----|----------|------------|-----|----------|------|
|          |                                 |                           | MIN        | NOM | MAX      | MIN        | NOM | MAX      |      |
| $V_{CC}$ | Supply voltage                  |                           | 4.5        | 5   | 5.5      | 4.5        | 5   | 5.5      | V    |
| $V_{IH}$ | High-level input voltage        | $V_{CC} = 4.5$ V to 5.5 V | 2          |     |          | 2          |     |          | V    |
| $V_{IL}$ | Low-level input voltage         | $V_{CC} = 4.5$ V to 5.5 V |            |     | 0.8      |            |     | 0.8      | V    |
| $V_I$    | Input voltage                   |                           | 0          |     | $V_{CC}$ | 0          |     | $V_{CC}$ | V    |
| $V_O$    | Output voltage                  |                           | 0          |     | $V_{CC}$ | 0          |     | $V_{CC}$ | V    |
| $t_t$    | Input transition rise/fall time |                           |            |     | 500      |            |     | 500      | ns   |
| $T_A$    | Operating free-air temperature  |                           | - 55       |     | 125      | - 40       |     | 85       | °C   |

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 5.3 Thermal Information

|                       |                                                       | SN74HCT373 |          |         |            | UNIT |
|-----------------------|-------------------------------------------------------|------------|----------|---------|------------|------|
|                       |                                                       | DW (SOIC)  | N (PDIP) | NS (SO) | PW (TSSOP) |      |
| THERMAL METRIC        |                                                       | 20 PINS    | 20 PINS  | 20 PINS | 20 PINS    |      |
| $R_{\theta JA}$       | Junction-to-ambient thermal resistance <sup>(1)</sup> | 109.1      | 84.6     | 113.4   | 131.8      | °C/W |
| $R_{\theta JC (top)}$ | Junction-to-case (top) thermal resistance             | 76         | 72.5     | 78.6    | 72.2       | °C/W |
| $R_{\theta JB}$       | Junction-to-board thermal resistance                  | 77.6       | 65.3     | 78.4    | 82.8       | °C/W |
| $\Psi_{JT}$           | Junction-to-top characterization parameter            | 51.5       | 55.3     | 47.1    | 21.5       | °C/W |
| $\Psi_{JB}$           | Junction-to-board characterization parameter          | 77.1       | 65.2     | 78.1    | 82.4       | °C/W |
| $R_{\theta JC (bot)}$ | Junction-to-case (bottom) thermal resistance          | N/A        | N/A      | N/A     | N/A        | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

## 5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                       | TEST CONDITIONS                                                      |                           | V <sub>CC</sub> | T <sub>A</sub> = 25°C |       |      | SN54HCT373 |       | SN74HCT373 |       | UNIT |
|---------------------------------|----------------------------------------------------------------------|---------------------------|-----------------|-----------------------|-------|------|------------|-------|------------|-------|------|
|                                 |                                                                      |                           |                 | MIN                   | TYP   | MAX  | MIN        | MAX   | MIN        | MAX   |      |
| V <sub>OH</sub>                 | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                  | I <sub>OH</sub> = – 20 mA | 4.5 V           | 4.4                   | 4.499 |      | 4.4        |       | 4.4        |       | V    |
|                                 |                                                                      | I <sub>OH</sub> = – 6 mA  |                 | 3.98                  | 4.3   |      | 3.7        |       | 3.84       |       |      |
| V <sub>OL</sub>                 | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                  | I <sub>OL</sub> = 20 mA   | 4.5 V           |                       | 0.001 | 0.1  |            | 0.1   |            | 0.1   | V    |
|                                 |                                                                      | I <sub>OL</sub> = 6 mA    |                 |                       | 0.17  | 0.26 |            | 0.4   |            | 0.33  |      |
| I <sub>I</sub>                  | V <sub>I</sub> = V <sub>CC</sub> or 0                                |                           | 5.5 V           |                       | ±0.1  | ±100 |            | ±1000 |            | ±1000 | nA   |
| I <sub>OZ</sub>                 | V <sub>O</sub> = V <sub>CC</sub> or 0                                |                           | 5.5 V           |                       | ±0.01 | ±0.5 |            | ±10   |            | ±5    | μA   |
| I <sub>CC</sub>                 | V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0            |                           | 5.5 V           |                       |       | 8    |            | 160   |            | 80    | μA   |
| ΔI <sub>CC</sub> <sup>(1)</sup> | One input at 0.5 V or 2.4 V,<br>Other inputs at 0 or V <sub>CC</sub> |                           | 5.5 V           |                       | 1.4   | 2.4  |            | 3     |            | 2.9   | mA   |
| C <sub>i</sub>                  |                                                                      |                           | 4.5 V to 5.5 V  |                       | 3     | 10   |            | 10    |            | 10    | pF   |

(1) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 5.5 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

|     |                              | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     | SN54HCT373 |     | SN74HCT373 |     | UNIT |
|-----|------------------------------|-----------------|-----------------------|-----|------------|-----|------------|-----|------|
|     |                              |                 | MIN                   | MAX | MIN        | MAX | MIN        | MAX |      |
| tw  | Pulse duration, LE high      | 4.5V            | 20                    |     | 30         |     | 25         |     | ns   |
|     |                              | 5.5V            | 17                    |     | 27         |     | 23         |     |      |
| tsu | Setup time, data before LE ↓ | 4.5V            | 10                    |     | 15         |     | 13         |     | ns   |
|     |                              | 5.5V            | 9                     |     | 14         |     | 12         |     |      |
| th  | Hold time, data after LE ↓   | 4.5V            | 10                    |     | 10         |     | 10         |     | ns   |
|     |                              | 5.5V            | 10                    |     | 10         |     | 10         |     |      |

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see [Parameter Measurement Information](#))

| PARAMETER        | FROM (INPUT) | TO (OUTPUT) | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     |     | SN54HCT373 |     | SN74HCT373 |     | UNIT |
|------------------|--------------|-------------|-----------------|-----------------------|-----|-----|------------|-----|------------|-----|------|
|                  |              |             |                 | MIN                   | TYP | MAX | MIN        | MAX | MIN        | MAX |      |
| t <sub>pd</sub>  | D            | Q           | 4.5 V           |                       | 25  | 35  |            | 53  |            | 44  | ns   |
|                  |              |             | 5.5 V           |                       | 21  | 32  |            | 48  |            | 40  |      |
|                  | LE           | Any Q       | 4.5 V           |                       | 28  | 35  |            | 53  |            | 44  |      |
|                  |              |             | 5.5 V           |                       | 25  | 32  |            | 48  |            | 40  |      |
| t <sub>en</sub>  | OE           | Any Q       | 4.5 V           |                       | 26  | 35  |            | 53  |            | 44  | ns   |
|                  |              |             | 5.5 V           |                       | 23  | 32  |            | 48  |            | 40  |      |
| t <sub>dis</sub> | OE           | Any Q       | 4.5 V           |                       | 23  | 35  |            | 53  |            | 44  | ns   |
|                  |              |             | 5.5 V           |                       | 22  | 32  |            | 48  |            | 40  |      |
| t <sub>t</sub>   |              | Any Q       | 4.5 V           |                       | 10  | 12  |            | 18  |            | 15  | ns   |
|                  |              |             | 5.5 V           |                       | 9   | 11  |            | 16  |            | 14  |      |

## 5.7 Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 150$  pF (unless otherwise noted) (see [Parameter Measurement Information](#))

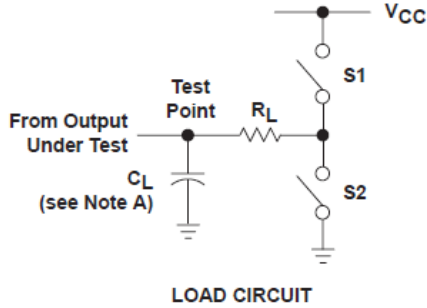
| PARAMETER | FROM<br>(INPUT) | TO<br>(OUTPUT) | $V_{CC}$ | $T_A = 25^\circ\text{C}$ |     |     | SN54HCT373 |     | SN74HCT373 |     | UNIT |
|-----------|-----------------|----------------|----------|--------------------------|-----|-----|------------|-----|------------|-----|------|
|           |                 |                |          | MIN                      | TYP | MAX | MIN        | MAX | MIN        | MAX |      |
| $t_{pd}$  | D               | Q              | 4.5 V    |                          | 32  | 52  |            | 79  |            | 65  | ns   |
|           |                 |                | 5.5 V    |                          | 27  | 47  |            | 71  |            | 59  |      |
|           | LE              | Any Q          | 4.5 V    |                          | 38  | 52  |            | 79  |            | 65  |      |
|           |                 |                | 5.5 V    |                          | 36  | 47  |            | 71  |            | 59  |      |
| $t_{en}$  | $\overline{OE}$ | Any Q          | 4.5 V    |                          | 33  | 52  |            | 79  |            | 65  | ns   |
|           |                 |                | 5.5 V    |                          | 28  | 47  |            | 71  |            | 59  |      |
| $t_r$     |                 | Any Q          | 4.5 V    |                          | 18  | 42  |            | 63  |            | 53  | ns   |
|           |                 |                | 5.5 V    |                          | 16  | 38  |            | 57  |            | 48  |      |

## 5.8 Operating Characteristics

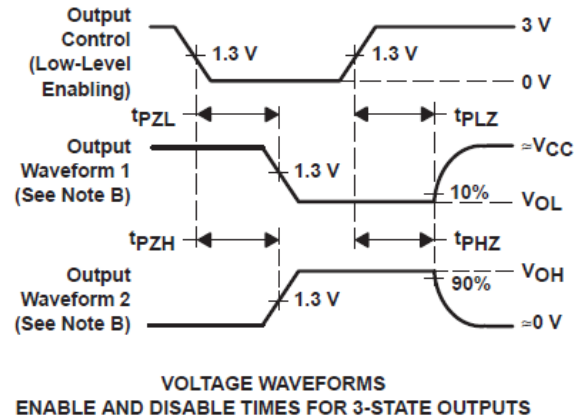
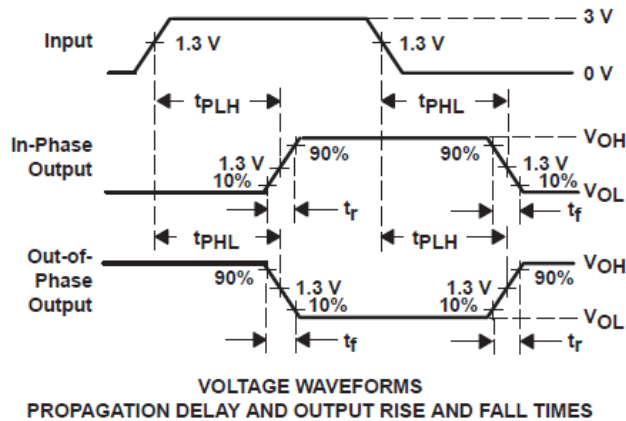
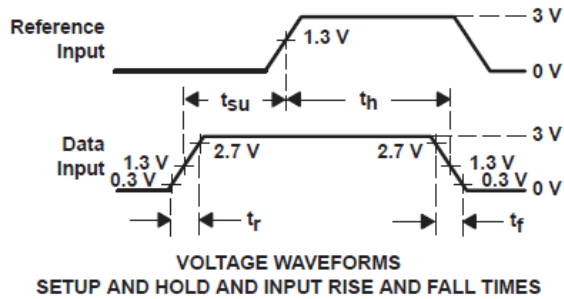
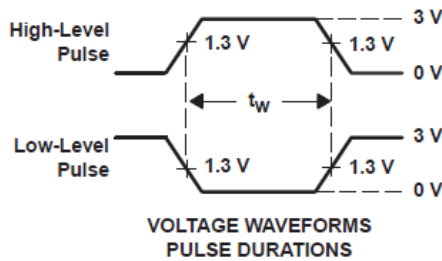
$T_A = 25^\circ\text{C}$

| PARAMETER |                                         | TEST CONDITIONS | TYP | UNIT |
|-----------|-----------------------------------------|-----------------|-----|------|
| $C_{pd}$  | Power dissipation capacitance per latch | No load         | 50  | pF   |

## 6 Parameter Measurement Information



| PARAMETER         | $R_L$        | $C_L$           | S1     | S2     |
|-------------------|--------------|-----------------|--------|--------|
| $t_{en}$          | 1 k $\Omega$ | 50 pF or 150 pF | Open   | Closed |
|                   |              |                 | Closed | Open   |
| $t_{dis}$         | 1 k $\Omega$ | 50 pF           | Open   | Closed |
|                   |              |                 | Closed | Open   |
| $t_{pd}$ or $t_t$ | —            | 50 pF or 150 pF | Open   | Open   |



- $C_L$  includes probe and test-fixture capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
- The outputs are measured one at a time with one input transition per measurement.
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

图 6-1. Load Circuit and Voltage Waveforms

## 7 Detailed Description

### 7.1 Overview

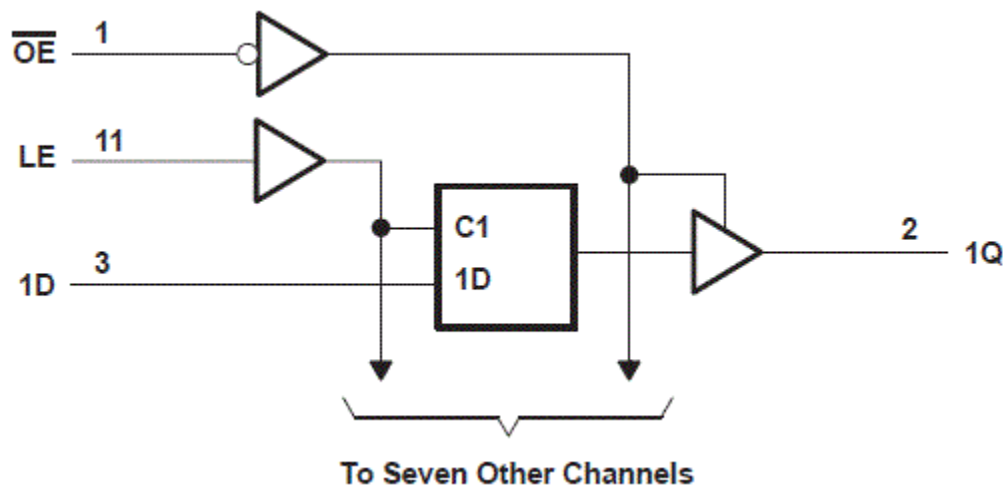
These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the ' HCT373 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

An output-enable ( $\overline{OE}$ ) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

### 7.2 Functional Block Diagram



### 7.3 Device Functional Modes

表 7-1. Function Table  
(Each Latch)

| INPUTS          |    |   | OUTPUT<br>Q |
|-----------------|----|---|-------------|
| $\overline{OE}$ | LE | D |             |
| L               | H  | H | H           |
| L               | H  | L | L           |
| L               | L  | X | $Q_0$       |
| H               | X  | X | Z           |

## 8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 9 Layout

### 9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 10.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 10.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

### 10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

### 10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.5 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

| Orderable part number            | Status<br>(1) | Material type<br>(2) | Package   Pins | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6)                     |
|----------------------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|-----------------------------------------|
| <a href="#">5962-86867012A</a>   | Active        | Production           | LCCC (FK)   20 | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-<br>86867012A<br>SNJ54HCT<br>373FK |
| <a href="#">5962-8686701RA</a>   | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8686701RA<br>SNJ54HCT373J          |
| <a href="#">5962-8686701VSA</a>  | Active        | Production           | CFP (W)   20   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8686701VS<br>A<br>SNV54HCT373W     |
| 5962-8686701VSA.A                | Active        | Production           | CFP (W)   20   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8686701VS<br>A<br>SNV54HCT373W     |
| <a href="#">JM38510/65453BRA</a> | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BRA                    |
| JM38510/65453BRA.A               | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BRA                    |
| <a href="#">JM38510/65453BSA</a> | Active        | Production           | CFP (W)   20   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BSA                    |
| JM38510/65453BSA.A               | Active        | Production           | CFP (W)   20   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BSA                    |
| <a href="#">M38510/65453BRA</a>  | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BRA                    |
| <a href="#">M38510/65453BSA</a>  | Active        | Production           | CFP (W)   20   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | JM38510/<br>65453BSA                    |
| <a href="#">SN54HCT373J</a>      | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | SN54HCT373J                             |
| SN54HCT373J.A                    | Active        | Production           | CDIP (J)   20  | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | SN54HCT373J                             |
| <a href="#">SN74HCT373DW</a>     | Obsolete      | Production           | SOIC (DW)   20 | -                     | -           | Call TI                              | Call TI                           | -40 to 85    | HCT373                                  |
| <a href="#">SN74HCT373DWR</a>    | Active        | Production           | SOIC (DW)   20 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HCT373                                  |
| SN74HCT373DWR.A                  | Active        | Production           | SOIC (DW)   20 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HCT373                                  |
| <a href="#">SN74HCT373N</a>      | Active        | Production           | PDIP (N)   20  | 20   TUBE             | Yes         | NIPDAU   NIPDAU                      | N/A for Pkg Type                  | -40 to 85    | SN74HCT373N                             |
| SN74HCT373N.A                    | Active        | Production           | PDIP (N)   20  | 20   TUBE             | Yes         | NIPDAU                               | N/A for Pkg Type                  | -40 to 85    | SN74HCT373N                             |
| SN74HCT373NE4                    | Active        | Production           | PDIP (N)   20  | 20   TUBE             | Yes         | NIPDAU                               | N/A for Pkg Type                  | -40 to 85    | SN74HCT373N                             |
| <a href="#">SN74HCT373NSR</a>    | Active        | Production           | SOP (NS)   20  | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HCT373                                  |

| Orderable part number         | Status<br>(1) | Material type<br>(2) | Package   Pins  | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6)                     |
|-------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|-----------------------------------------|
| SN74HCT373NSR.A               | Active        | Production           | SOP (NS)   20   | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HCT373                                  |
| <a href="#">SN74HCT373PW</a>  | Obsolete      | Production           | TSSOP (PW)   20 | -                     | -           | Call TI                              | Call TI                           | -40 to 85    | HT373                                   |
| <a href="#">SN74HCT373PWR</a> | Active        | Production           | TSSOP (PW)   20 | 2000   LARGE T&R      | Yes         | NIPDAU   NIPDAU                      | Level-1-260C-UNLIM                | -40 to 85    | HT373                                   |
| SN74HCT373PWR.A               | Active        | Production           | TSSOP (PW)   20 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HT373                                   |
| SN74HCT373PWR.B               | Active        | Production           | TSSOP (PW)   20 | 2000   LARGE T&R      | -           | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | HT373                                   |
| <a href="#">SNJ54HCT373FK</a> | Active        | Production           | LCCC (FK)   20  | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-<br>86867012A<br>SNJ54HCT<br>373FK |
| SNJ54HCT373FK.A               | Active        | Production           | LCCC (FK)   20  | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-<br>86867012A<br>SNJ54HCT<br>373FK |
| <a href="#">SNJ54HCT373J</a>  | Active        | Production           | CDIP (J)   20   | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8686701RA<br>SNJ54HCT373J          |
| SNJ54HCT373J.A                | Active        | Production           | CDIP (J)   20   | 20   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8686701RA<br>SNJ54HCT373J          |
| <a href="#">SNJ54HCT373W</a>  | Active        | Production           | CFP (W)   20    | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | SNJ54HCT373W                            |
| SNJ54HCT373W.A                | Active        | Production           | CFP (W)   20    | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | SNJ54HCT373W                            |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN54HCT373, SN54HCT373-SP, SN74HCT373 :**

- Catalog : [SN74HCT373](#), [SN54HCT373](#)
- Military : [SN54HCT373](#)
- Space : [SN54HCT373-SP](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74HCT373DWR | SOIC         | DW              | 20   | 2000 | 330.0              | 24.4               | 10.8    | 13.3    | 2.7     | 12.0    | 24.0   | Q1            |
| SN74HCT373DWR | SOIC         | DW              | 20   | 2000 | 330.0              | 24.4               | 10.9    | 13.3    | 2.7     | 12.0    | 24.0   | Q1            |
| SN74HCT373NSR | SOP          | NS              | 20   | 2000 | 330.0              | 24.4               | 8.4     | 13.0    | 2.5     | 12.0    | 24.0   | Q1            |
| SN74HCT373PWR | TSSOP        | PW              | 20   | 2000 | 330.0              | 16.4               | 6.95    | 7.0     | 1.4     | 8.0     | 16.0   | Q1            |

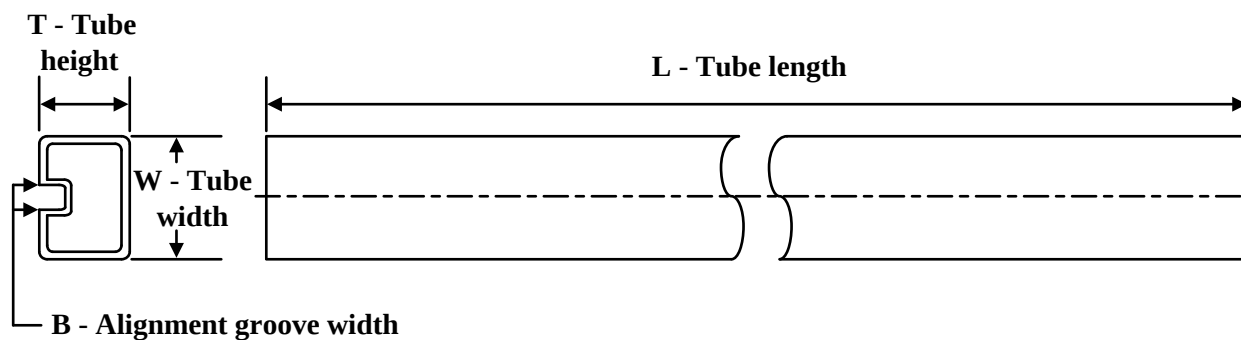
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74HCT373DWR | SOIC         | DW              | 20   | 2000 | 356.0       | 356.0      | 45.0        |
| SN74HCT373DWR | SOIC         | DW              | 20   | 2000 | 356.0       | 356.0      | 45.0        |
| SN74HCT373NSR | SOP          | NS              | 20   | 2000 | 356.0       | 356.0      | 45.0        |
| SN74HCT373PWR | TSSOP        | PW              | 20   | 2000 | 353.0       | 353.0      | 32.0        |

## TUBE



\*All dimensions are nominal

| Device             | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|--------------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-86867012A     | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| 5962-8686701VSA    | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| 5962-8686701VSA.A  | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| JM38510/65453BSA   | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| JM38510/65453BSA.A | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| M38510/65453BSA    | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| SN74HCT373N        | N            | PDIP         | 20   | 20  | 506    | 13.97  | 11230  | 4.32   |
| SN74HCT373N.A      | N            | PDIP         | 20   | 20  | 506    | 13.97  | 11230  | 4.32   |
| SN74HCT373NE4      | N            | PDIP         | 20   | 20  | 506    | 13.97  | 11230  | 4.32   |
| SNJ54HCT373FK      | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| SNJ54HCT373FK.A    | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| SNJ54HCT373W       | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |
| SNJ54HCT373W.A     | W            | CFP          | 20   | 25  | 506.98 | 26.16  | 6220   | NA     |

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



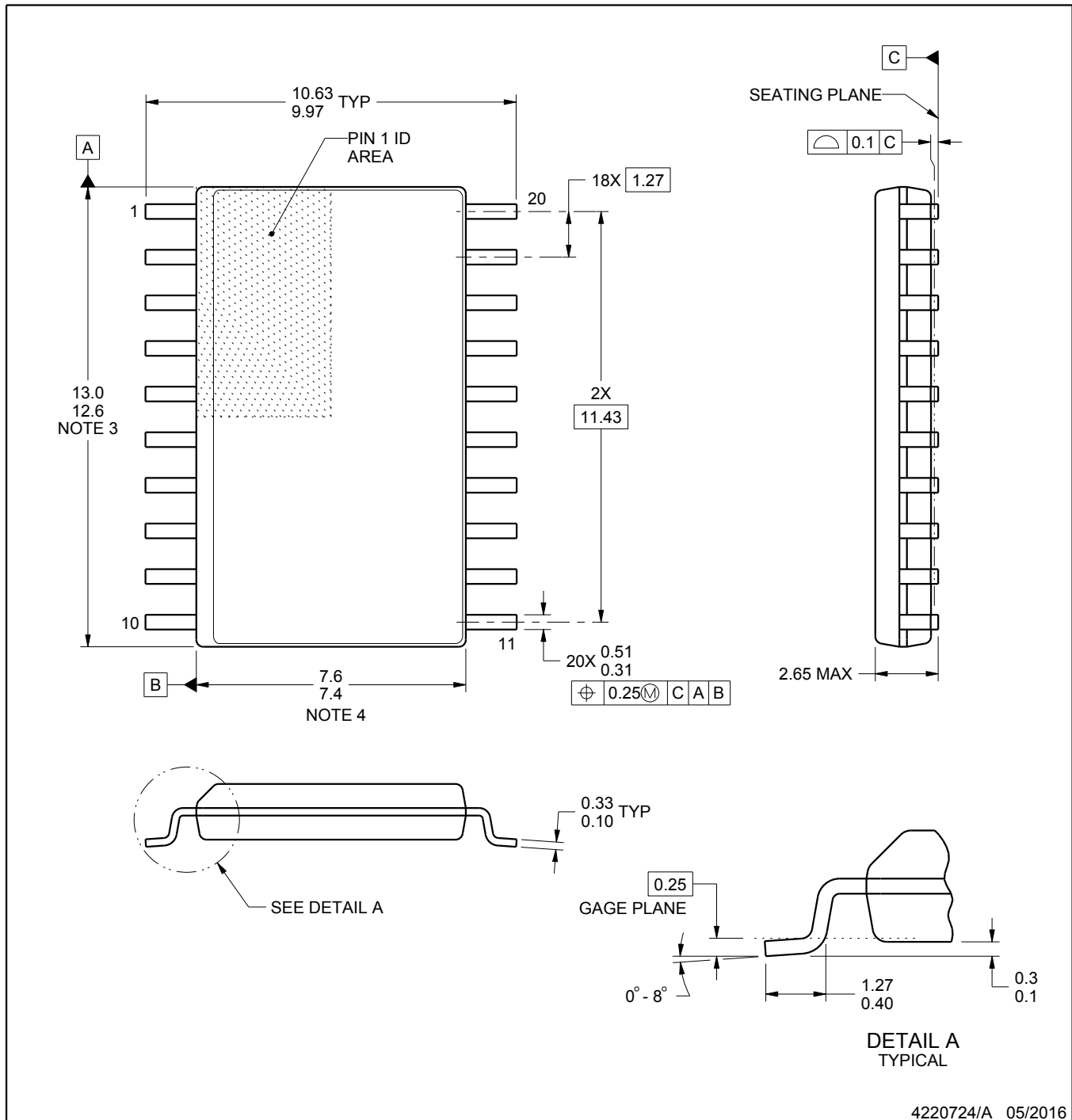
| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



## NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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